

# Preface

The twenty-fifth International Symposium for Testing and Failure Analysis is vastly different from the first ISTFA. In those days failure analysis was fairly simple as were the devices. Today, many advanced analytical tools and techniques must be employed as the geometry has diminished and the technologies have become increasingly complicated by mixing signals and employing more and more new materials.

This Failure Analysis symposium brings you the latest in techniques along with novel approaches to solving some unique and more common problems. We have even added a Software session this year and will continue to add categories as methods and devices change each year.

The new millennium will bring even more changes at a faster rate than we can imagine. We rely on you, the Failure Analysts and Test engineers to develop and share new methodologies with your colleagues at our annual Symposium and Seminar sessions. Engineers from around the world participate each year to share their work and network with each other. These are exciting times in the semiconductor/electronic industry and this years efforts reflect the newest ways to solve our ever more challenging fabrication, assembly and packaging problems.

Thanks to everyone who contributed to this year's symposium which took considerable effort to switch to electronic format for the symposium presentations. I invite you to join again next year and encourage you to share your experience at a future symposium.